

TGF150

Leader Tech's TGF150 series thermal gap filler is mainly filled with low specific gravity and high thermal conductivity filler. The unique orientation technology is used to maximize the high thermal conductivity of the filler. Due to the low filling ratio, the material has an excellent toughness and surface softness that can more effectively fill the air gap and reduce the interface thermal resistance. It has an ultra-high thermal conductivity, which is an ideal thermal conductive material.

Features:

- Soft
- Low thermal resistance
- Lightweight
- Excellent thermal stability property
- RoHS and Halogen Compliant

Applications:

- Military Industry
- Radar
- Large Servers
- GPU and Image processor
- High frequency Netcom equipment

Storage Conditions:

- Store in the darkness
- Storage Temperature: ≤ 30 °C
- Storage Humidity: $\leq 70\%$
- When stacking the parts, the parts should not be higher than 7 layers or more than 1mm

Shelf Life:

- Stored at storage conditions: Two years
- Stored in unqualified storage conditions: 6 months

Properties:

Item	Parameter	Unit	Test Method
Color	Black	-	Visual
Specification	150*150	mm	ASTM D5947
Thickness	0.5 ~ 2	mm	ASTM D374
Hardness	45(±5)	Shore 00	ASTM D2240
Density	1.5(±0.2)	g/cc	ASTM D792
Tensile Strength	≥0.12	Mpa	ASTM D412
Elongation	≥200	%	ASTM D412
TML	0.49	%	ASTM E595
UL Certification	V-0	-	UL94
Operating Temperature	-50 ~ 180	°C	IEC 600068-2-14

Thermal Characteristics:

Thermal Conductivity	15	W / m·K	ASTM D5470
Thermal Resistance	≤0.15(@20PSI/1mm)	°Cin ² /W	ASTM D5470

Electrical Properties:

Volume Resistivity	≥10 ¹⁰	Ω·cm	ASTM D257
Dielectric constant	15	@1MHz	ASTM D150